

**LTM8048 45-BGA-PBF 11.25mm X 9mm X 4.92mm - SOLDER D/A (TABLE OF MATERIAL DECLARATION)**

Contains > 1000ppm of Lead in the terminations

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1069	Barium Compounds	7727-43-7	0.00283	2.65
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.02117	19.80
				Copper Metal	7440-50-8	0.05893	55.11
				Copper Compounds	147-14-8	0.00002	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00015	0.14
				Nickel	7440-02-0	0.00073	0.68
				Zinc	7440-66-6	0.00012	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.01665	15.57
				Acrylic Resin	non-disclosure	0.00541	5.06
				Epoxy Resin	non-disclosure	0.00002	0.02
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica Amorphous	7631-86-9	0.00006	0.06
				Talc;not containing fiber like asbestos	14807-96-6	0.00033	0.31
				Aromatic carbonyl compounds	non-disclosure	0.00031	0.29
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00004	0.04
				Leveling agent and others	non-disclosure	0.00013	0.12
2	Solder Paste	Alloy	0.0086	Sn	7440-31-5	0.00822	95.0
				Sb	7440-36-0	0.00043	5.0
3	Passive/Active Components		0.2405	Ni Oxide	1313-99-1	0.02060	8.57
				Cu Oxide	1317-38-0	0.00693	2.88
				Zn Oxide	1314-13-2	0.03137	13.04
				Fe Oxide	1309-37-1	0.11432	47.53
				iron Powder (Fe)	7439-89-6	0.00335	1.39
				Copper (Cu)	7440-50-8	0.04893	20.34
				Nickel (Ni)	7440-02-0	0.00141	0.58
				Tin (Sn)	7440-31-5	0.00352	1.46
				Ceramic (Ba Compounds)	12047-27-7	0.01008	4.19
4	Active Ics	Silicon	0.0032	Silicon	7440-21-3	0.00322	100
5	Wire	Gold	0.0002	Au	7440-57-5	0.00025	99.99
6	Solder Ball	63Sn/37Pb	0.0860	Sn	7440-31-5	0.05418	63.00
				Pb	7439-92-1	0.03182	37.00
7	Encapsulation	Epoxy Resin	0.7098	Fused Silica	60676-86-0	0.54795	77.2
				Epoxy Resin	non-disclosure	0.06317	8.9
				Phenol Resin	non-disclosure	0.06317	8.9
				Crytalline Silica	14808-60-7	0.02129	3.0
				Carbon Black	1333-86-4	0.00355	0.5
				Metal Hydroxide	non-disclosure	0.01065	1.5
Total Package Weight			1.1553				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts